

Bumping Site Transfer for Cu Pillar Bumped Products

Qualification Results Summary of Cu Pillar Bumped Products at Chipbond Plant 4

TEST	SPECIFICATION	SAMPLE SIZE	RESULTS
High Temperature Operating Life Test (HTOL)	JESD22-A108	6x77	PASS
Temperature Cycle Test (TCT)*	JESD22-A104	9x77	PASS
Unbiased Highly Accelerated Stress Test (uHAST)*	JESD22-A118	6x77	PASS
Highly Accelerated Stress Test (HAST)*	JESD22-A110	9x77	PASS
Solder Heat Resistance Test (SHR)*	J-STD-020	9x11	PASS
High Temperature Storage (HTS)	JESD22-A103	3x77	PASS

* Preconditioned per JEDEC/IPC J-STD0020.